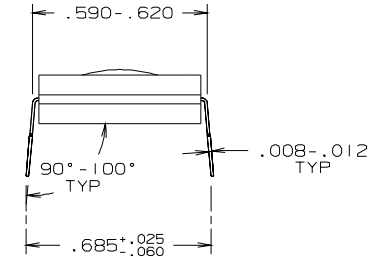
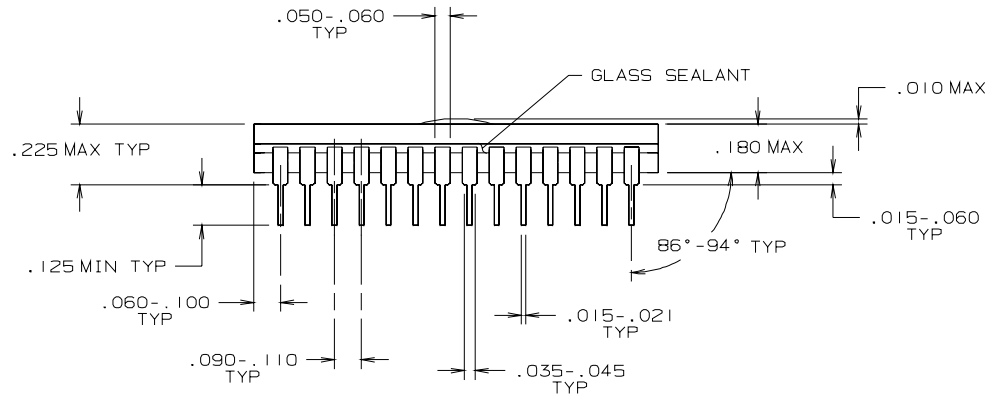
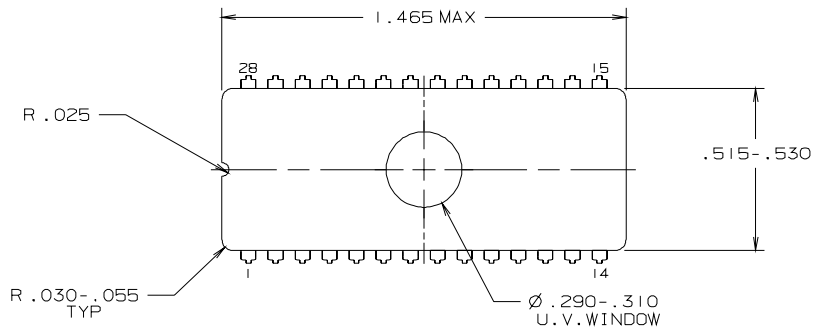


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
D	REVISE AND REDRAW	08999	01/07/92	DEG/



MIL/AERO CONFIGURATION CONTROL MIL-M-38510 CONFIGURATION CONTROL

NOTES: UNLESS OTHERWISE SPECIFIED

- LEAD FINISH TO BE ONE OF THE FOLLOWING:
 - 200 MICROINCHES MINIMUM SOLDER MEASURED AT THE CREST OF THE MAJOR FLATS.
 - 200-800 MICROINCHES TIN PLATE OVER 50-300 MICROINCHES NICKEL UNDERPLATE OR BASIS METAL.
 - 50-100 MICROINCHES GOLD OVER 50-350 MICROINCHES NICKEL UNDERPLATE.
- LEAD FINISH, NICKEL UNDERPLATE AND BASIS METAL SHALL CONFORM TO THE REQUIREMENTS OF MIL-M-38510.
- NO JEDEC REGISTRATION AS OF 12/16/91.

APPROVALS	DATE	NATIONAL SEMICONDUCTOR CORPORATION		
DRAWN	D. E. GRADY	01/07/92	2900 Semiconductor Drive, Santa Clara, CA 95052-8090	
DFTG. CHK.			CERDIP (JQ), 28 LEAD, EPROM, MEDIUM WINDOW	
ENGR. CHK.				
APPROVAL				
PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
	N/A	C	MKT-J28CQ	D
	FORMERLY:	N/A	SHEET	OF